MODEL
ATRM-4000
Automatic Wafer De-Lamination System

Outline

The ATRM-4000 is the idela system for removing lamination tape from wafers, following the backgrind process.

Features

● State-of -the -art design to maintain the integrity of the lamination area and to achieve the best footprint.
● Special table prevents from wafer breakage.
● Ease of operation
● FOUP option
● AGV and OHT protocol options
● Option: UV unit
● Applicable to 8"and 12" dia-wafer

For 300mm wafers

Specification		ATRM-4000
Throughput		70 wafers/hour（Depend on data setting）
Wafer Size		8 inch、12 inch
Tape Width		8 inch：W 50〜75mm 、12 inch：W 75〜100mm
Utilities	Power	AC100V　Single phase 50／60Hz　2.5 KVA
	Air	Pressure 0.4Mpa　100Nl/min
	Vacuum sourse	—74Kpa
Dimensions		D 1,575 × W 1,350 × H 1,800mm
Weight		600 kg

System appearance and specifications are subject to change without prior notice from the supplier.